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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

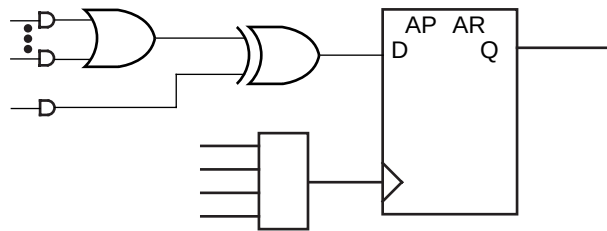
Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

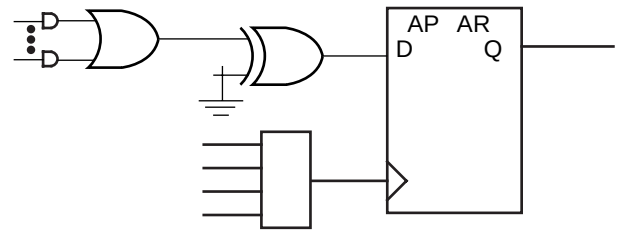
Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-64-32-12vi48

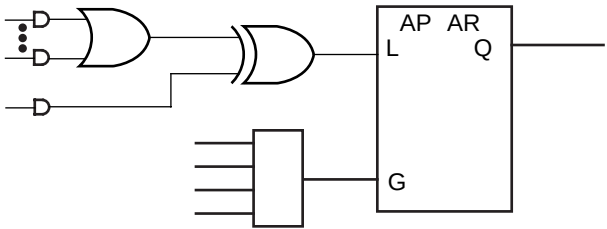
The flip-flop can be configured as a D-type or T-type latch. J-K or S-R registers can be synthesized. The primary flip-flop configurations are shown in Figure 6, although others are possible. Flip-flop functionality is defined in Table 8. Note that a J-K latch is inadvisable as it will cause oscillation if both J and K inputs are HIGH.



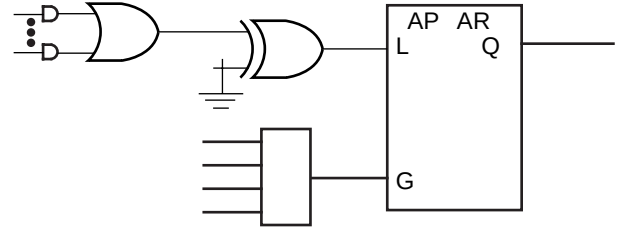
a. D-type with XOR



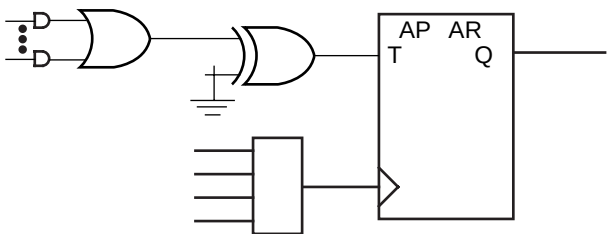
b. D-type with programmable D polarity



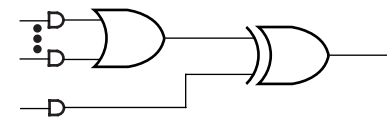
c. Latch with XOR



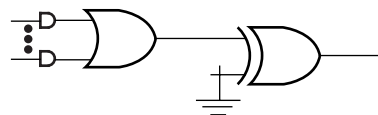
d. Latch with programmable D polarity



e. T-type with programmable T polarity



f. Combinatorial with XOR



g. Combinatorial with programmable polarity

Figure 6. Primary Macrocell Configurations

17466G-011

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	$\overline{Q}$
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

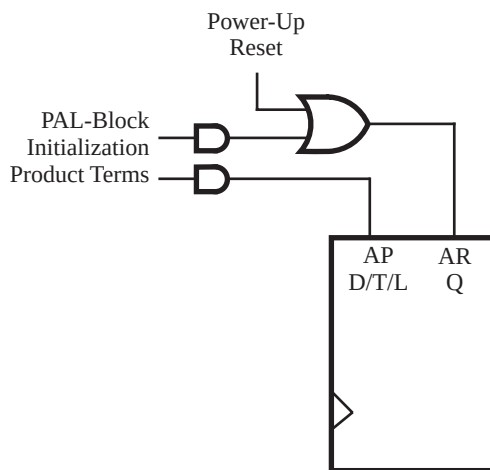
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

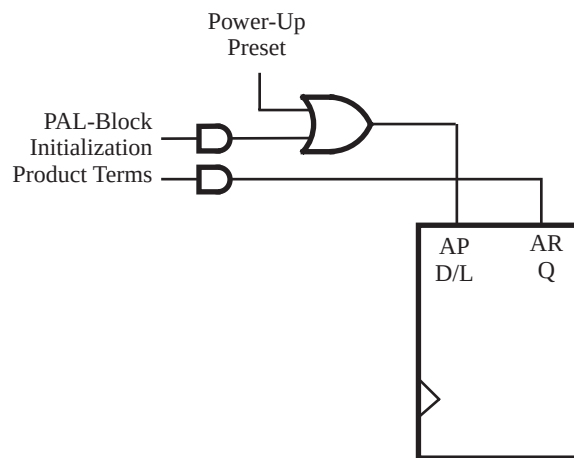
The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset

17466G-012



b. Power-up preset

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

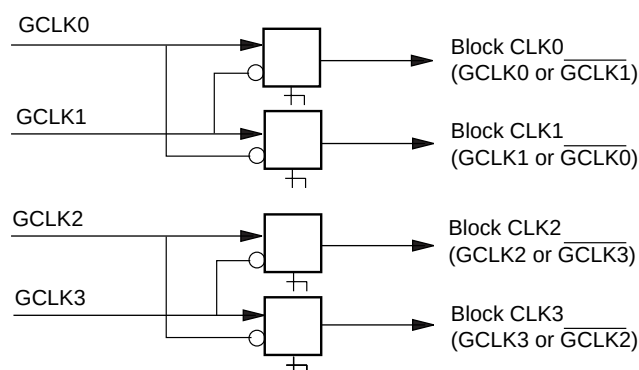
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{\text{GCLK1}}$	GCLK1	X	X
GCLK0	$\overline{\text{GCLK0}}$	X	X
$\overline{\text{GCLK1}}$	$\overline{\text{GCLK0}}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)
X	X	$\overline{\text{GCLK3}}$ (GCLK1)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

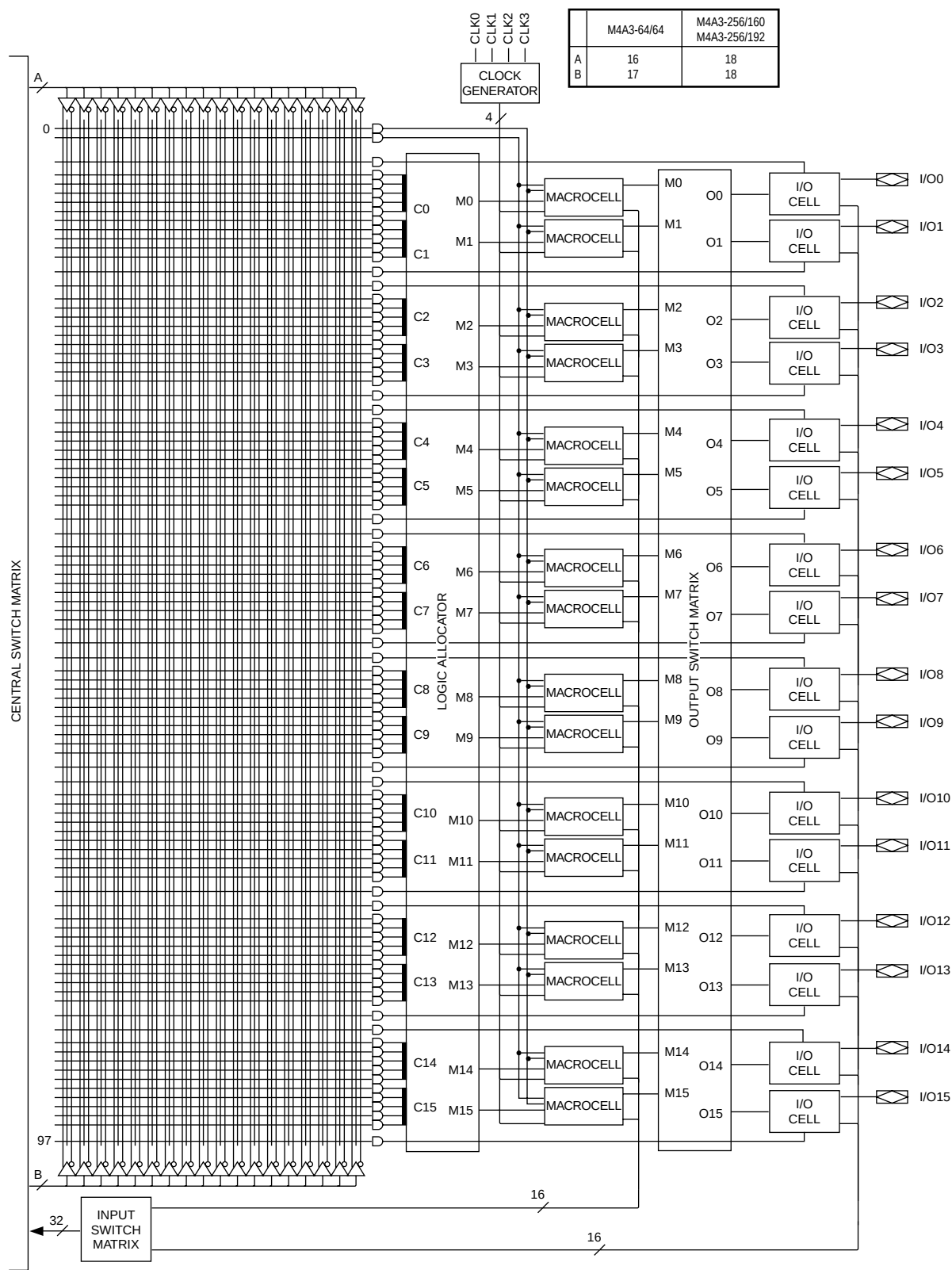
All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.



17466H-41

Figure 17. PAL Block for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio (except M4A (3,5)-32/32)

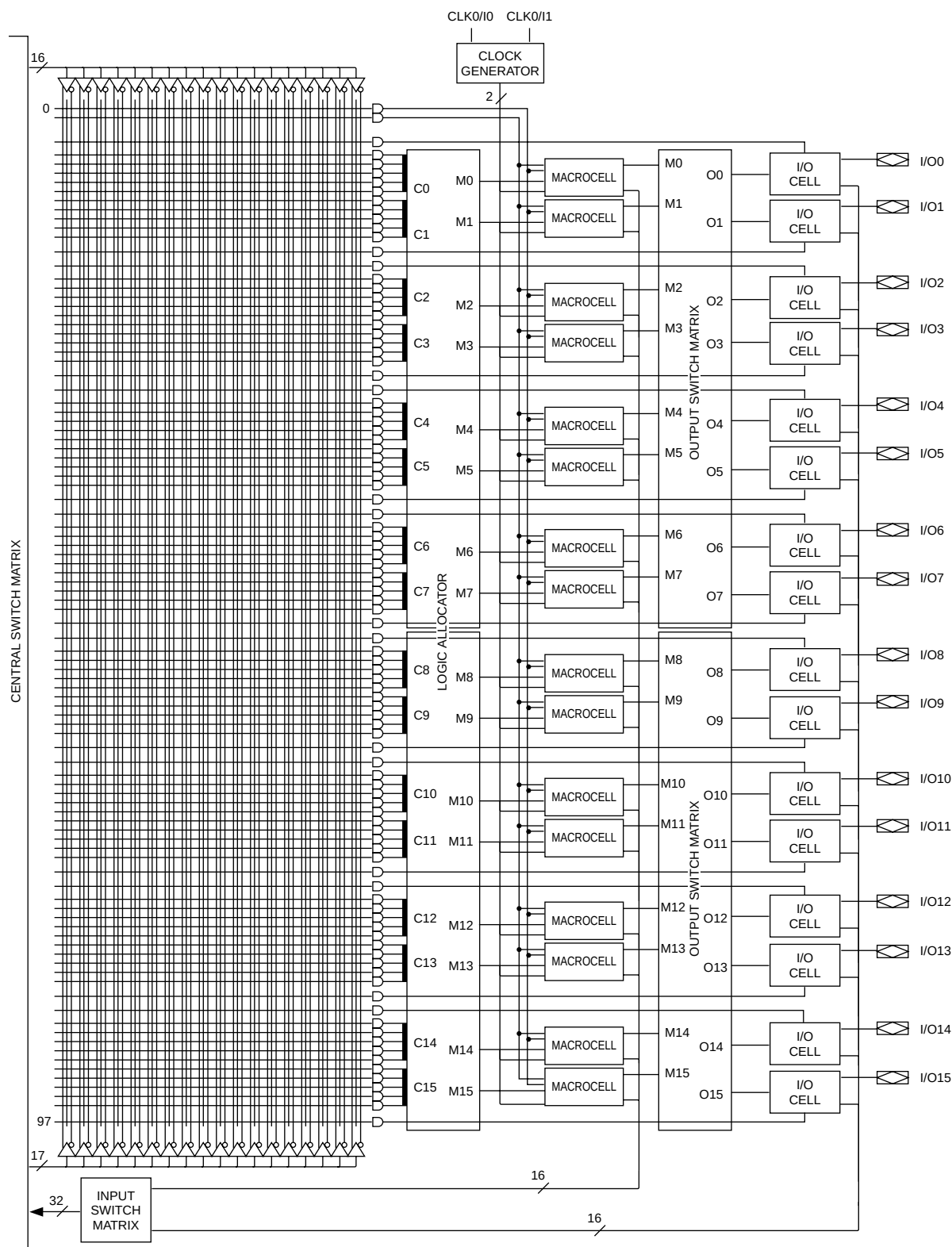
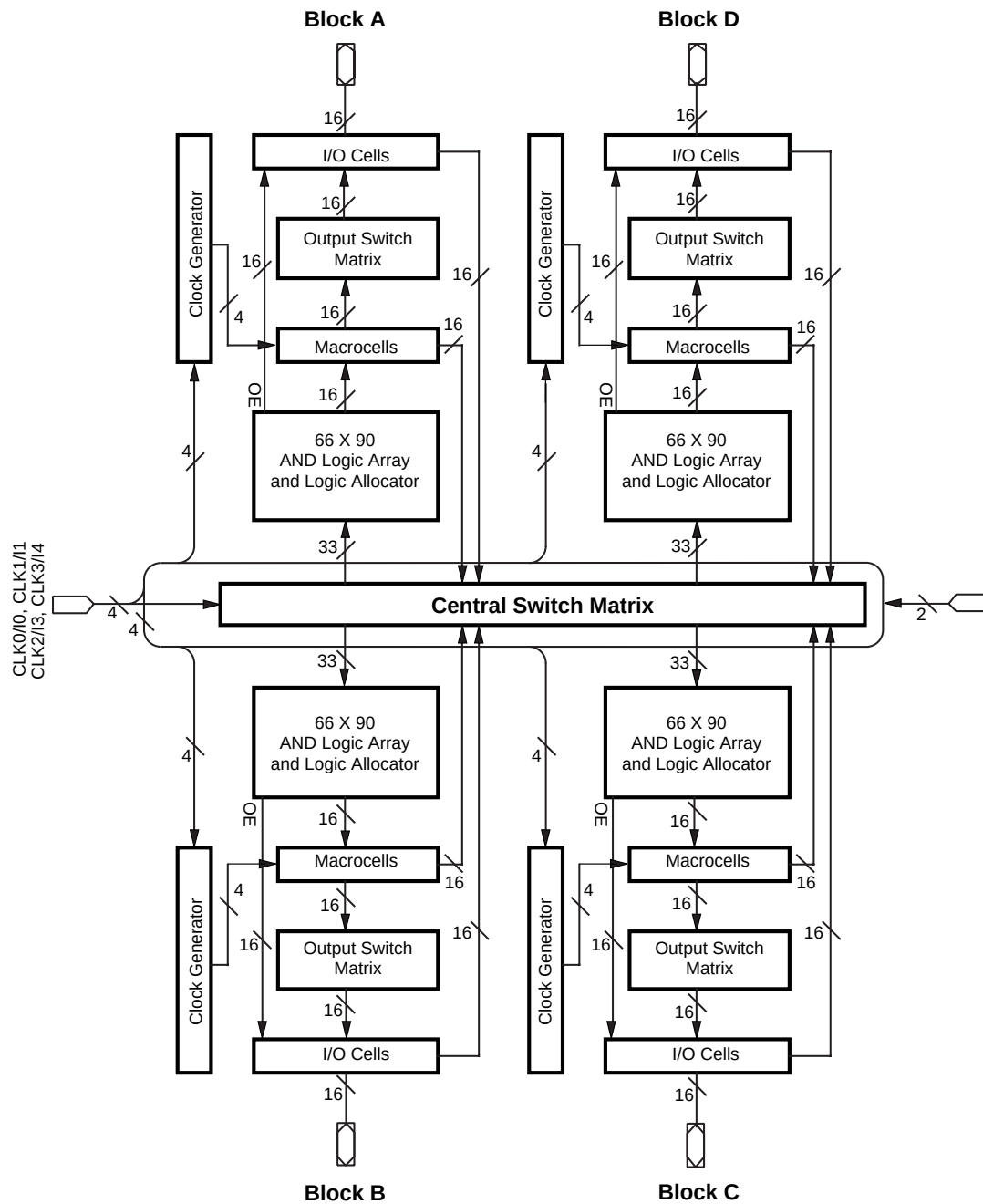


Figure 18. PAL Block for M4A (3,5)-32/32

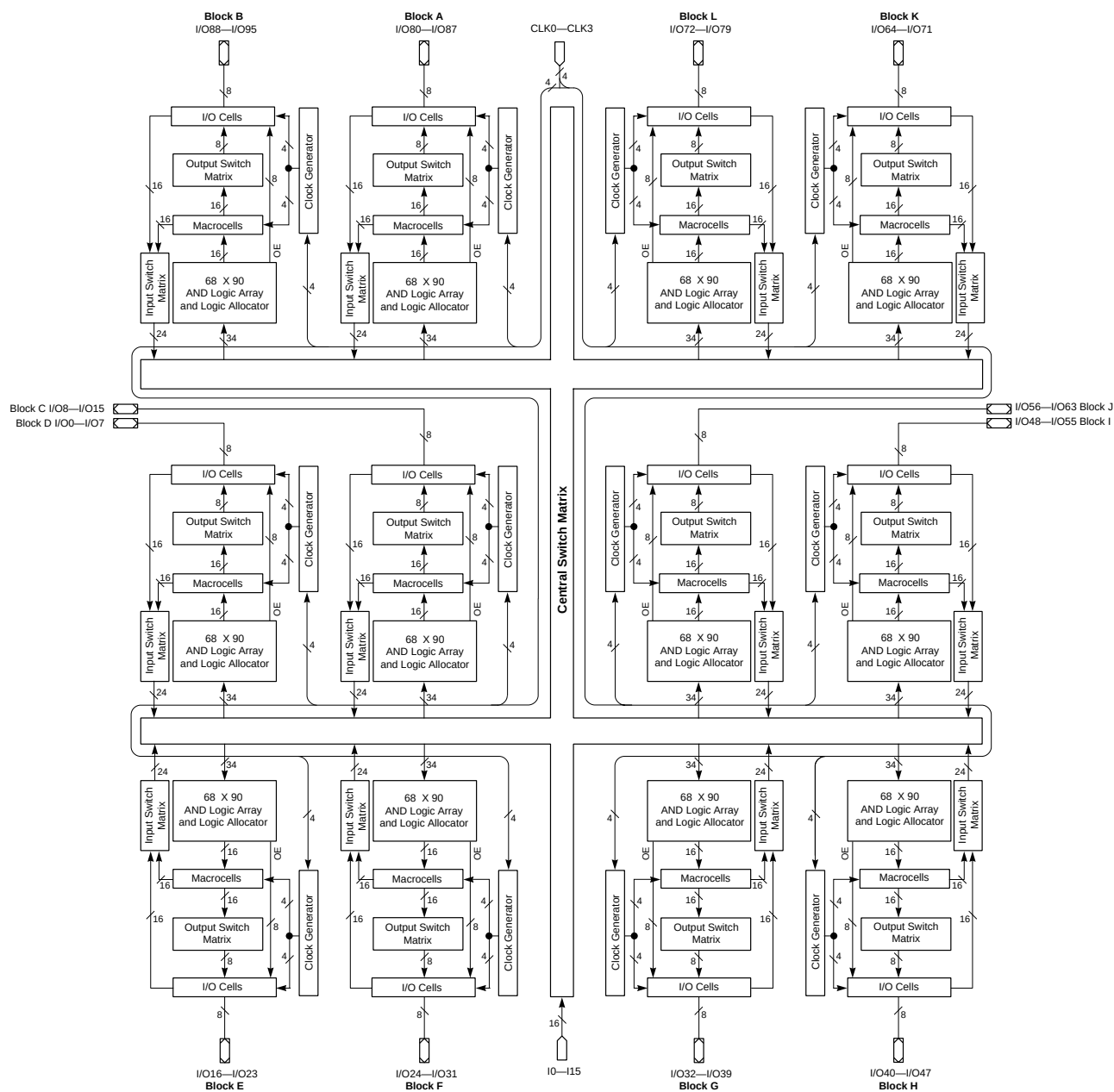
17466H-042

BLOCK DIAGRAM – M4A3-64/64



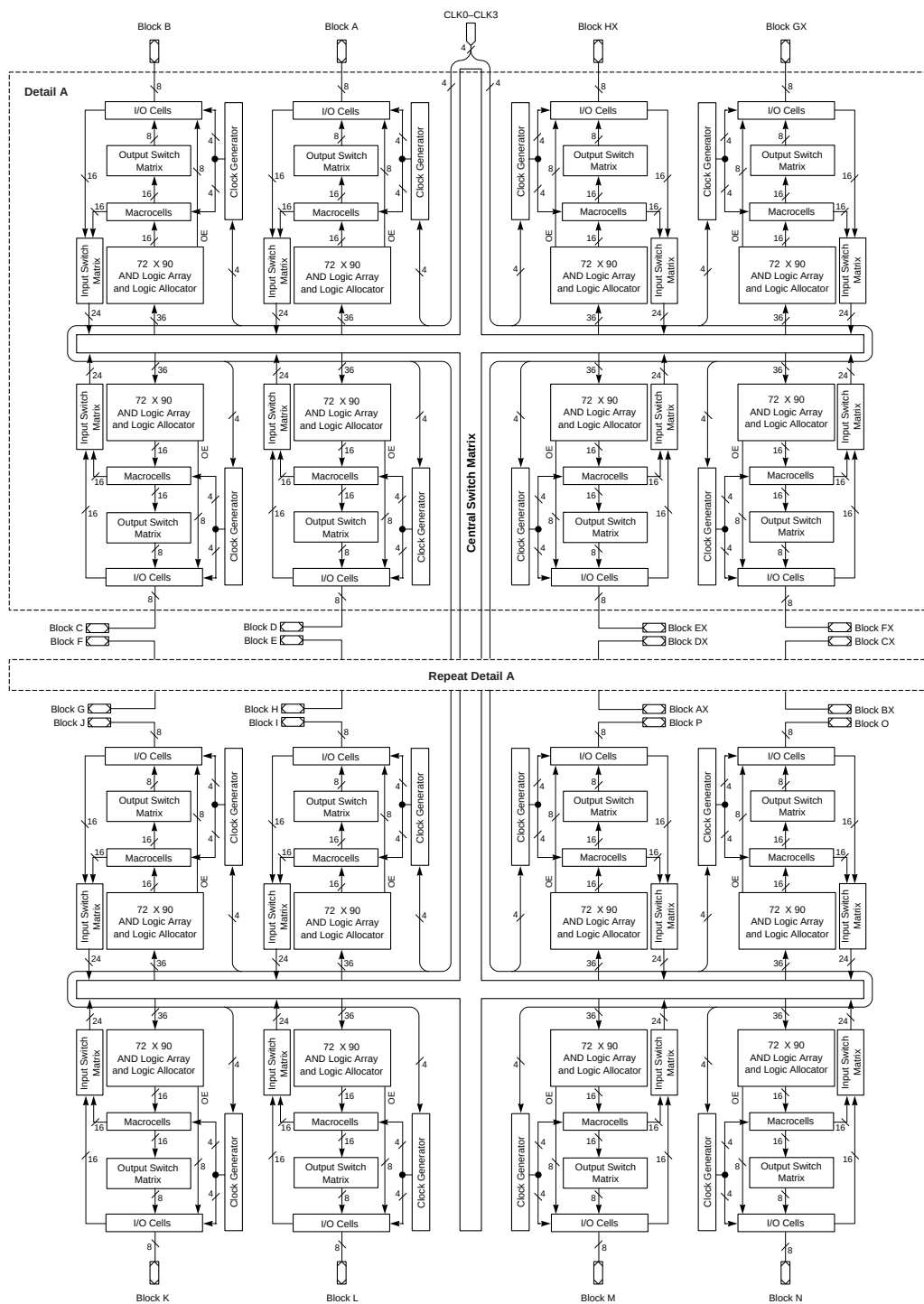
17466H-020A

BLOCK DIAGRAM – M4A(3,5)-192/96



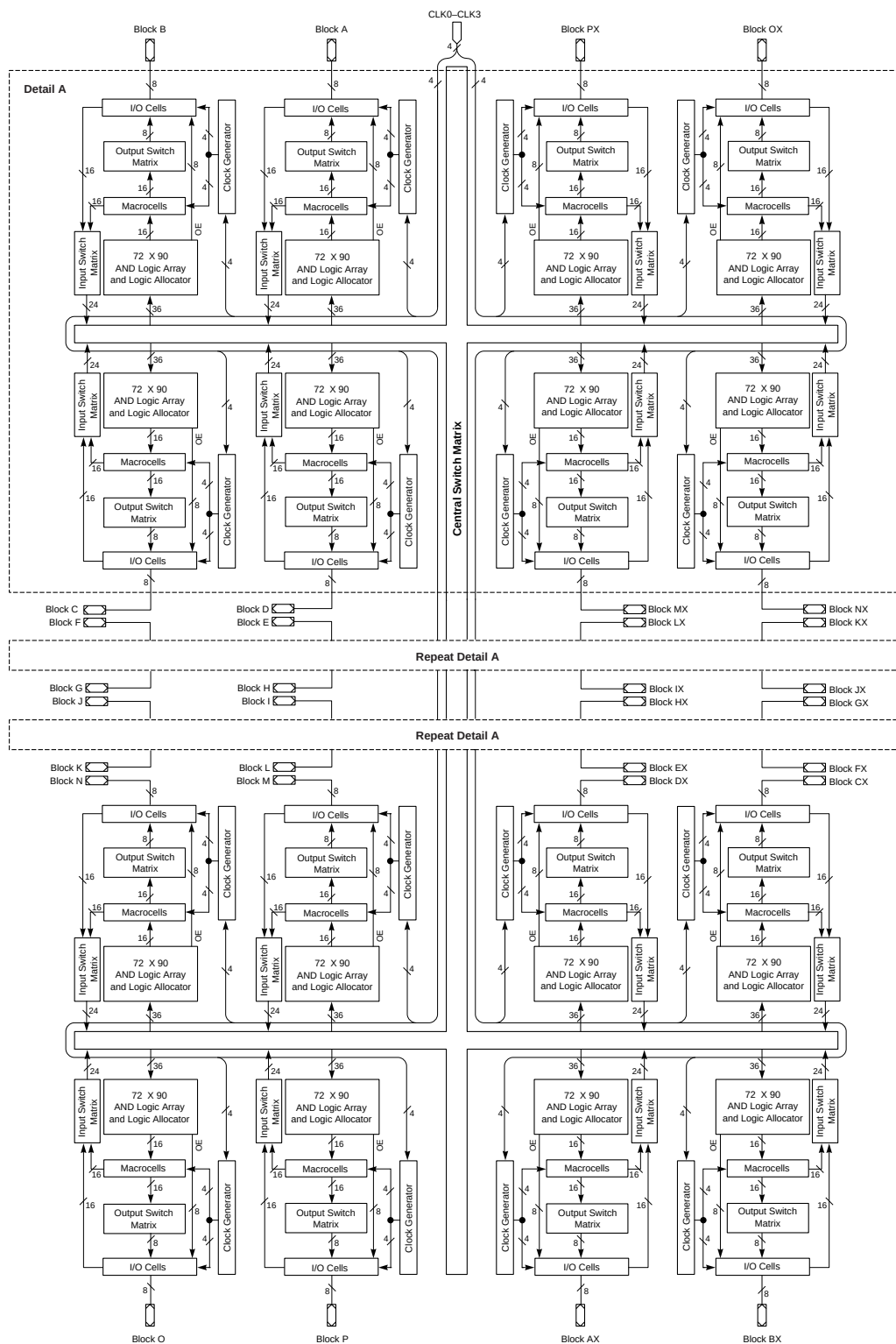
17466G-067

BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

BLOCK DIAGRAM - M4A3-512/160, M4A3-512/192, M4A3-512/256



17466G-068

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground -0.5 V to +7.0 V
 DC Input Voltage -0.5 V to $V_{CC} + 0.5$ V
 Static Discharge Voltage 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.50 V to +5.5 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

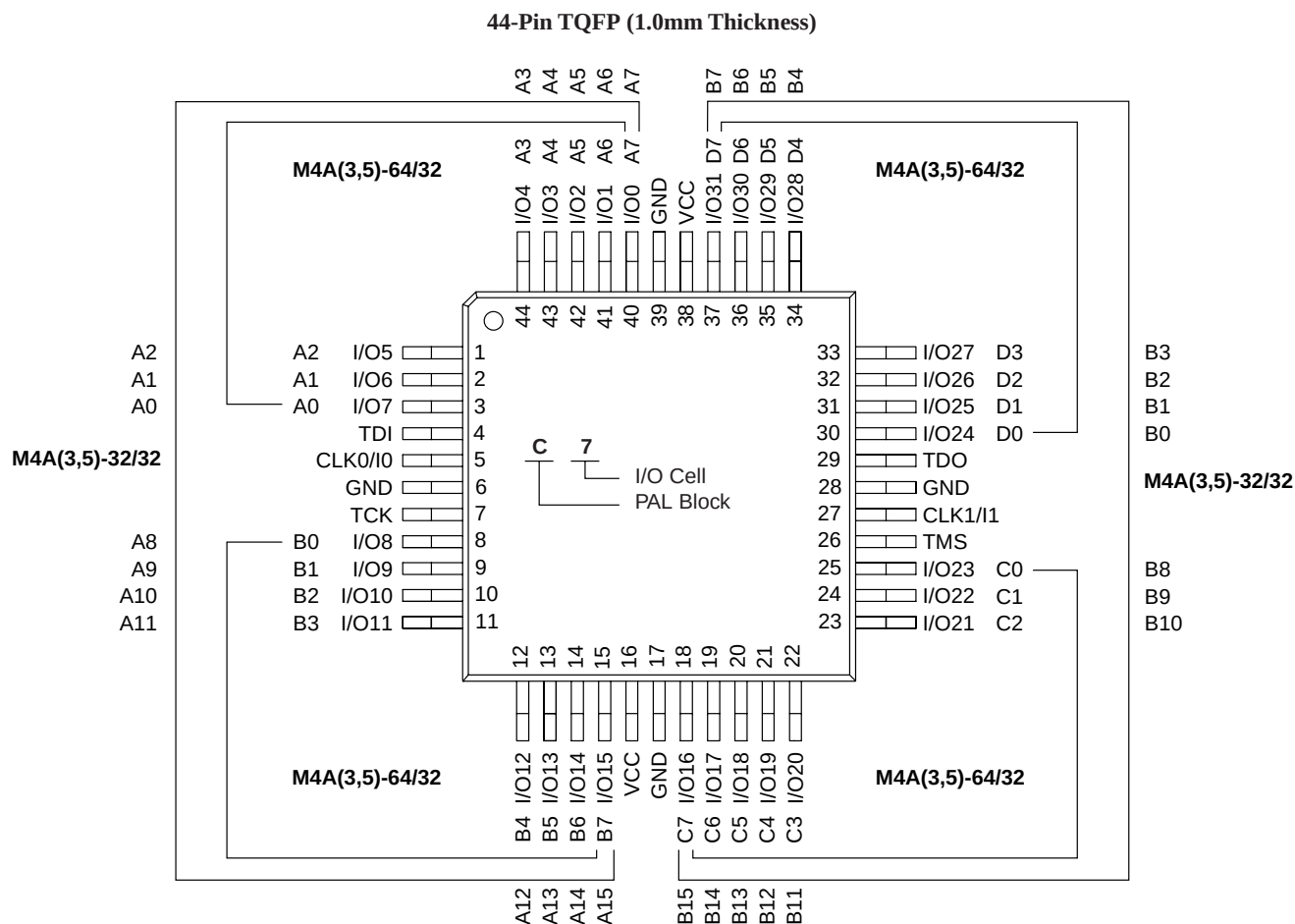
Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100$ μA , $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25$ V, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0$ V, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5$ V, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 $V_{OUT} = 0.5$ V has been chosen to avoid test problems caused by tester ground degradation.

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

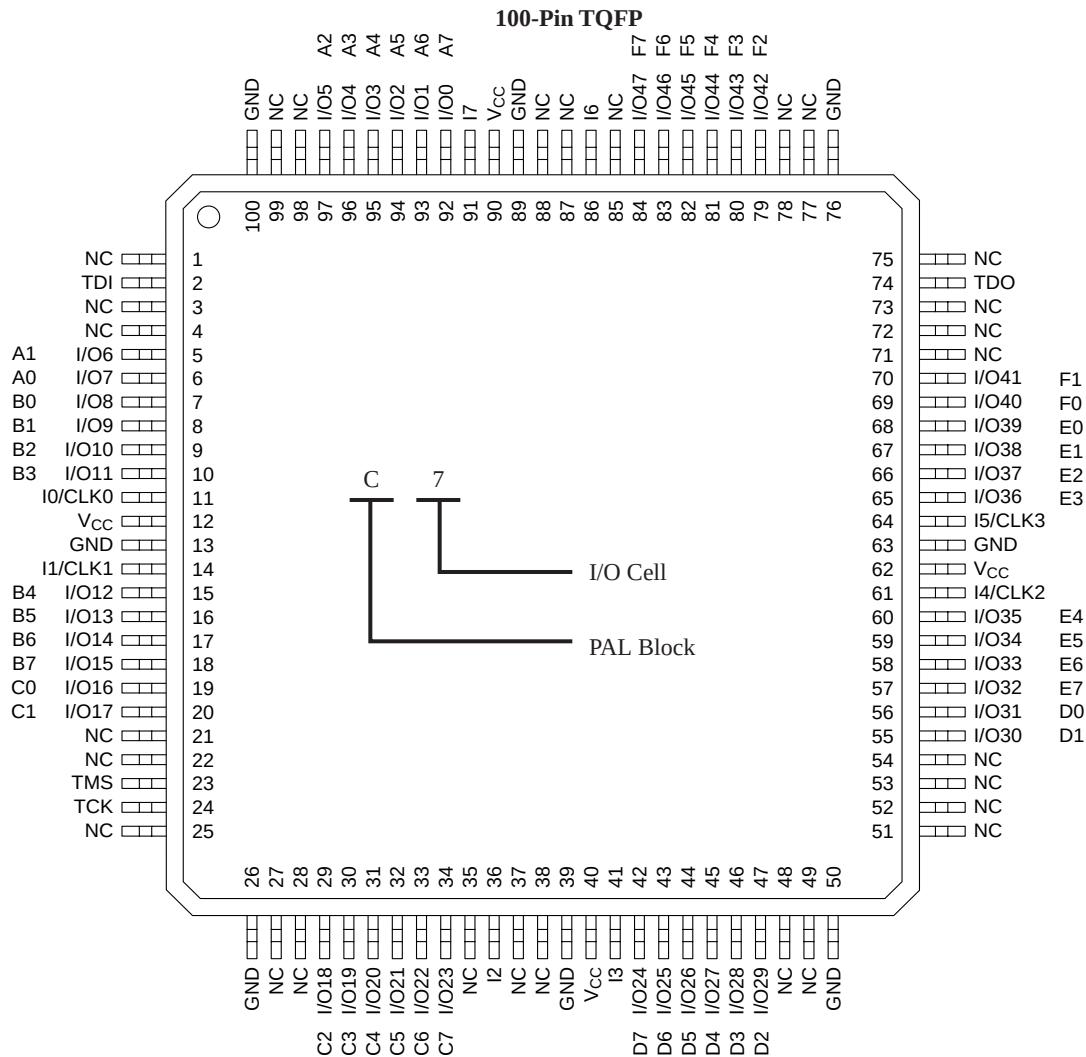
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-96/48)

Top View



17466G-029

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

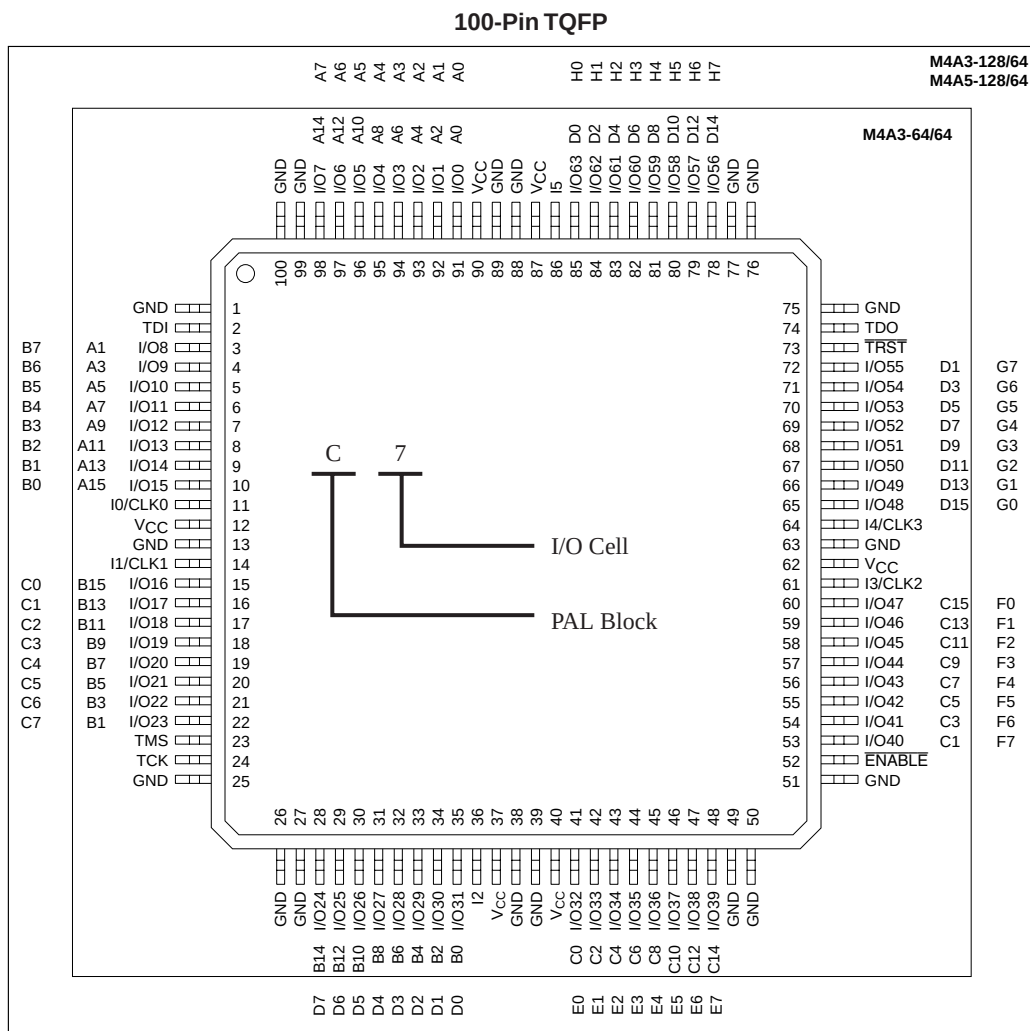
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

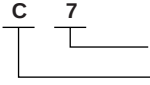
TRST = Test Reset

ENABLE = Program

256-BALL BGA CONNECTION DIAGRAM (M4A3-256/128)

Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	N/C	GND	I/O108 N4	I/O105 N1	GND	I/O100 M4	I/O96 M0	GND	GND	GND	GND	I/O95 L0	I/O91 L4	GND	I/O87 K0	N/C	GND	GND	GND	A
B	GND	I/O113 O6	N/C	I/O109 N5	I/O106 N2	I/O103 M7	I/O102 M6	I/O98 M2	N/C	I11	N/C	N/C	I/O93 L2	I/O89 L6	I/O88 L7	I/O85 K2	I/O83 K4	I/O82 K5	N/C	GND	B
C	I/O116 O3	N/C	VCC	TRST	I/O111 N7	I/O107 N3	I/O104 N0	I/O101 M5	I/O97 M1	N/C	I10	I/O94 L1	I/O90 L5	I/O86 K1	I/O84 K3	I/O80 K7	ENABLE	VCC	I/O78 J6	I/O74 J2	C
D	I/O120 P7	I/O117 O2	I/O112 O7	VCC	VCC	I/O110 N6	VCC	N/C	I/O99 M3	N/C	I9	I/O92 L3	N/C	VCC	I/O81 K6	VCC	VCC	I/O79 J7	I/O75 J3	I/O71 I7	D
E	I/O123 P4	I/O119 O0	I/O114 O5	TDI	PIN DESIGNATIONS CLK = Clock GND = Ground I = Input I/O = Input/Output N/C = No Connect VCC = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out TRST = Test Reset ENABLE = Program  I/O Cell PAL Block												TDO	I/O77 J5	I/O72 J0	I/O68 I4	E
F	GND	I/O122 P5	I/O118 O1	I/O115 O4													I/O76 J4	I/O73 J1	I/O69 I5	GND	F
G	I12	I/O125 P2	I/O121 P6	VCC													VCC	I/O70 I6	I/O65 I1	I8	G
H	GND	I/O127 P0	I/O126 P1	I/O124 P3													I/O67 I3	I/O66 I2	I/O64 I0	GND	H
J	N/C	N/C	N/C	I13													I7	N/C	N/C	N/C	J
K	GND	CLK3	N/C	N/C													N/C	N/C	CLK2	N/C	K
L	N/C	CLK0	N/C	N/C													N/C	N/C	CLK1	GND	L
M	N/C	N/C	N/C	I0													I6	N/C	I/O63 H0	I/O62 H1	M
N	GND	I/O0 A0	I/O2 A2	I/O3 A3													I/O60 H3	I/O61 H2	I/O59 H4	GND	N
P	I1	I/O1 A1	I/O6 A6	VCC													VCC	I/O57 H6	I/O58 H5	I5	P
R	GND	I/O5 A5	I/O9 B1	N/C													I/O51 G4	I/O54 G1	I/O56 H7	GND	R
T	I/O4 A4	I/O8 B0	I/O12 B4	TCK													TMS	I/O50 G5	I/O55 G0	N/C	T
U	I/O7 A7	I/O11 B3	I/O15 B7	VCC	VCC	I/O18 C5	VCC	I/O24 D7	I/O29 D2	I2	N/C	I/O35 E3	N/C	VCC	N/C	VCC	VCC	I/O48 G7	I/O53 G2	N/C	U
V	I/O10 B2	I/O13 B5	VCC	I/O16 C7	I/O17 C6	I/O21 C2	I/O23 C0	I/O27 D4	I/O31 D0	I3	N/C	I/O33 E1	I/O37 E5	I/O41 F1	I/O43 F3	I/O46 F6	I/O47 F7	VCC	I/O52 G3	N/C	V
W	GND	I/O14 B6	N/C	N/C	I/O19 C4	I/O22 C1	I/O25 D6	I/O28 D3	N/C	N/C	I4	N/C	I/O34 E2	I/O38 E6	I/O39 E7	I/O42 F2	I/O45 F5	N/C	I/O49 G6	GND	W
Y	GND	GND	GND	N/C	I/O20 C3	GND	I/O26 D5	I/O30 D1	GND	GND	GND	GND	I/O32 E0	I/O36 E4	GND	I/O40 F0	I/O44 F4	GND	N/C	GND	Y
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

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256-BALL BGA CONNECTION DIAGRAM - (M4A3-384/192)

Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1			
A	GND	I/O11 FX7	GND	I/O44 FX6	I/O58 CX6	GND	I/O70 CX2	I/O76 DX6	GND	GND	GND	GND	I/O108 AX5	I/O116 BX0	GND	I/O128 BX7	I/O134 O3	GND	GND	GND	A		
B	GND	I/O12 GX7	I/O28 FX5	I/O45 FX3	I/O59 CX7	I/O64 CX5	I/O71 CX3	I/O77 DX7	I/O84 DX5	I/O90 DX2	I/O96 AX0	I/O102 AX3	I/O109 AX6	I/O117 BX1	I/O122 BX4	I/O129 BX6	I/O135 O4	I/O148 O6	I/O164 O7	GND	B		
C	I/O0 GX6	I/O13 GX5	VCC	I/O46 FX4	I/O60 FX2	I/O65 FX1	I/O72 CX4	I/O78 CX0	I/O85 DX4	I/O91 DX1	I/O97 AX1	I/O103 AX4	I/O110 BX2	I/O118 BX5	I/O123 O0	I/O130 O1	I/O136 O5	VCC	I/O165 N7	I/O181 N6	C		
D	I/O1 EX7	I/O14 GX3	I/O29 GX4	VCC	VCC	I/O66 FX0	VCC	I/O79 CX1	I/O86 DX3	I/O92 DX0	I/O98 AX2	I/O104 AX7	I/O111 B3X	VCC	I/O124 O2	VCC	VCC	I/O149 N4	I/O166 N5	I/O182 P7	D		
E	I/O2 EX0	I/O15 GX0	I/O30 GX1	TDI	PIN DESIGNATIONS CLK = Clock GND = Ground I = Input I/O = Input/Output N/C = No Connect VCC = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out C7 I/O Cell PAL Block														TDO	I/O150 N2	I/O167 N3	I/O183 P6	E
F	GND	I/O16 EX1	I/O31 EX6	I/O47 GX2															I/O137 N1	I/O151 N0	I/O168 P5	GND	F
G	I/O3 HX6	I/O17 EX4	I/O32 EX5	VCC															VCC	I/O152 P4	I/O169 P3	I/O184 M7	G
H	GND	I/O18 HX5	I/O33 EX2	I/O48 EX3															I/O138 P2	I/O153 P1	I/O170 P0	GND	H
J	I/O4 HX0	I/O19 HX1	I/O34 HX4	I/O49 HX7															I/O139 M6	I/O154 M5	I/O171 M4	I/O185 M3	J
K	GND	CLK3	I/O35 HX2	I/O50 HX3															I/O140 M0	I/O155 M1	CLK2	I/O186 M2	K
L	I/O5 A2	CLK0	I/O36 A0	I/O51 A1															I/O141 L3	I/O156 L4	CLK1	GND	L
M	I/O6 A4	I/O20 A3	I/O37 A5	I/O52 A6															I/O142 L6	I/O157 L5	I/O172 L0	I/O187 L1	M
N	GND	I/O21 A7	I/O38 D0	I/O53 D1															I/O143 I5	I/O158 I0	I/O173 L7	GND	N
P	I/O7 D2	I/O22 D3	I/O39 D4	VCC															VCC	I/O159 I4	I/O174 I1	I/O188 L2	P
R	GND	I/O23 D5	I/O40 D6	I/O54 D7	I/O144 K5	I/O160 K0	I/O175 I3	GND	R														
T	I/O8 B3	I/O24 B0	I/O41 B7	TCK	TMS	I/O161 K4	I/O176 K1	I/O189 I2	T														
U	I/O9 B4	I/O25 B1	I/O42 B6	VCC	VCC	I/O67 C0	VCC	I/O80 F0	I/O87 E5	I/O93 E2	I/O99 H2	I/O105 H5	I/O112 G0	VCC	I/O125 J1	VCC	VCC	I/O162 K7	I/O177 K2	I/O190 I6	U		
V	I/O10 B5	I/O26 B2	VCC	I/O55 C5	I/O61 C2	I/O68 C1	I/O73 F4	I/O81 F1	I/O88 E4	I/O94 E1	I/O100 H1	I/O106 H4	I/O113 G1	I/O119 G4	I/O126 J0	I/O131 J2	I/O145 J5	VCC	I/O178 K3	I/O191 I7	V		
W	GND	I/O27 C7	I/O43 C6	I/O56 C3	I/O62 F7	I/O69 F5	I/O74 F3	I/O82 E7	I/O89 E3	I/O95 E0	I/O101 H0	I/O107 H3	I/O114 H7	I/O120 G3	I/O127 G5	I/O132 G7	I/O146 J4	I/O163 J6	I/O179 J7	GND	W		
Y	GND	GND	GND	I/O57 C4	I/O63 F6	GND	I/O75 F2	I/O83 E6	GND	GND	GND	GND	I/O115 H6	I/O121 G2	GND	I/O133 G6	I/O147 J3	GND	I/O180 K6	GND	Y		
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1			

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5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32	-55, -7, -10	JC, VC, VC48
M4A5-96/48		VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JJ, VI, VI48
M4A5-64/32	-7, -10, -12	JJ, VI, VI48
M4A5-96/48		VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A3-64/64		VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160	-7, -10	YNC
M4A3-256/192		FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/32		VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96	-10, -12	VNI
M4A3-256/128		FANI, YNI
M4A3-256/160		YNI
M4A3-256/192	-10, -12, -14	FANI
M4A3-384/192		FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A5-96/48		VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-64/32		VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.

Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.